

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

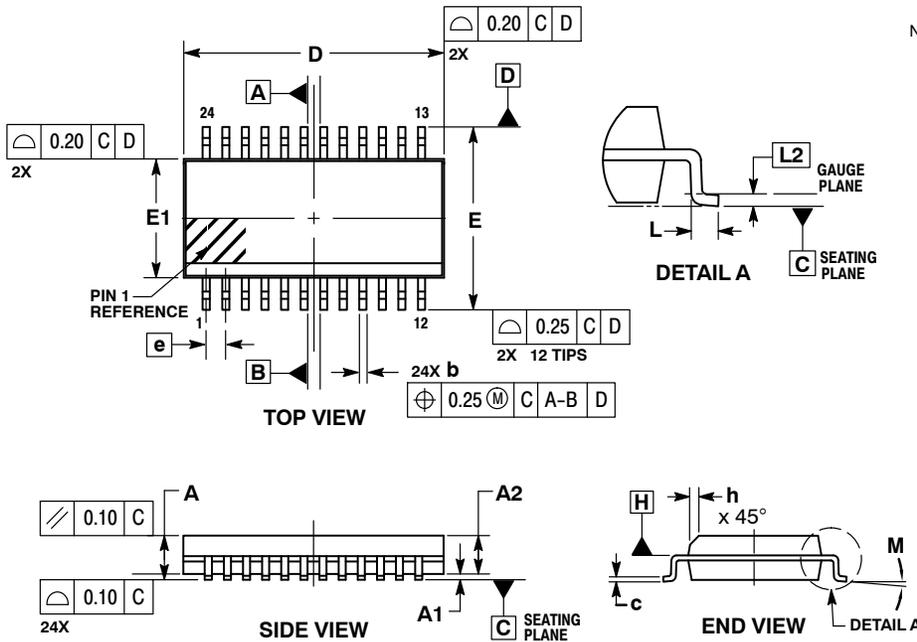
ON Semiconductor®



SCALE 1:1

SSOP24 NB
CASE 565AL-01
ISSUE O

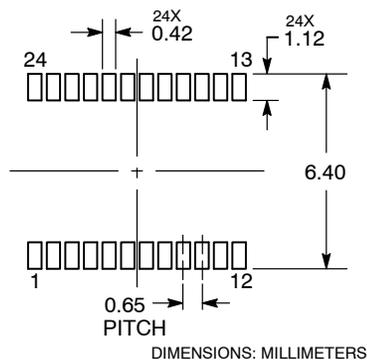
DATE 06 JUL 2010



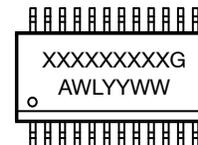
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 PER SIDE. D AND E1 ARE DETERMINED AT DATUM H.
 5. DATUMS A AND B ARE DETERMINED AT DATUM H.

MILLIMETERS		
DIM	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
A2	1.25	1.50
b	0.20	0.30
c	0.19	0.25
D	8.65 BSC	
E	6.00 BSC	
E1	3.90 BSC	
e	0.65 BSC	
h	0.22	0.50
L	0.40	1.27
L2	0.25 BSC	
M	0°	8°

RECOMMENDED SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

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